AMENDMENTS TO THE SPECIFICATION:

Please replace the following numbered paragraphs with the following rewritten paragraphs:

Referring to Figure 5A, another embodiment of a first ply 28AA is illustrated. The first layer 28AA includes a release film such as an etched fluorinated ethylene propylene (FEP) film which forms the inner surface 34 (also illustrated in Figure 1) of the semi-rigid mold member 28. The FEP film is applied to one surface of the fluoroelastomeric sheet and the sieve member 30 is applied dry to the opposite surface. The sieve member 30 will thereby be sandwiched between the first ply 28AA and the second ply 28B (Figure 2) but the sieve member 30 is not pressed into the first ply 28A. In other words, the sieve member is between the first and second ply of the semi-rigid mold member 28 and the total height h of the fluoroelastomeric sheet and the FEP of ply 28AA film does not include the sieve member 30. Laying up additional plys with or without inserts as described above then completes the semi-rigid mold member 28. This embodiment does not substantially embed the sieve member into the first ply 28AA and positions the sieve member 30 further away from the inner surface 34 to accommodate pin reveal lengths that are longer.